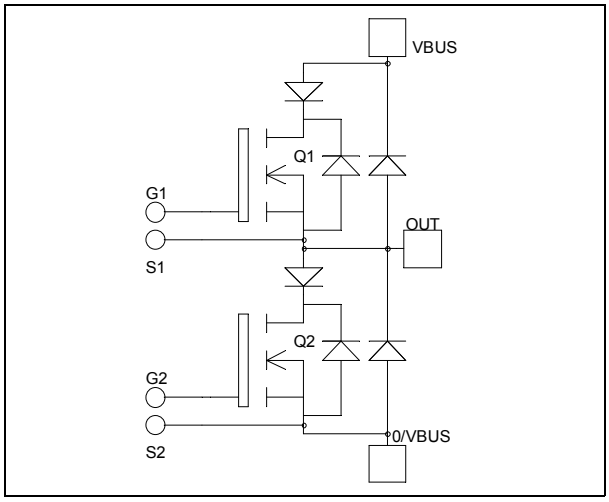
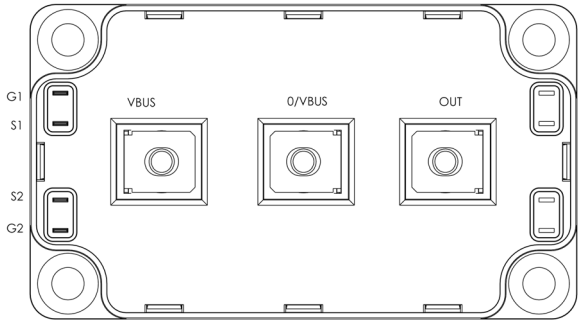
APTM120A20SG

Phase leg
Series & parallel diodes
MOSFET Power Module

V_{DSS} = 1200V
R_{DSon} = 200mΩ typ @ Tj = 25°C
I_D = 50A @ Tc = 25°C





Application

- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7® MOSFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Fast intrinsic reverse diode
  - Avalanche energy rated
  - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

All ratings @ T_j = 25°C unless otherwise specified

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		1200	V
I_D	Continuous Drain Current	T_c = 25°C	50	A
		T_c = 80°C	37	
I_{DM}	Pulsed Drain current		200	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		240	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	1250	W
I_{AR}	Avalanche current (repetitive and non repetitive)		12	A
E_{AR}	Repetitive Avalanche Energy		30	mJ
E_{AS}	Single Pulse Avalanche Energy		1300	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
I_{DSS}	Zero Gate Voltage Drain Current	V_{GS} = 0V,V_{DS} = 1200V			1.5	mA
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 25A		200	240	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 6mA	3		5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V, V_{DS} = 0V			±600	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		15.2		nF
C_{oss}	Output Capacitance			2.2		
C_{rss}	Reverse Transfer Capacitance			0.42		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 600V I_D = 50A		600		nC
Q_{gs}	Gate – Source Charge			84		
Q_{gd}	Gate – Drain Charge			390		
$T_{d(on)}$	Turn-on Delay Time	**Inductive switching @ 125°C** V_{GS} = 15V V_{Bus} = 800V I_D = 50A R_G =0.8Ω		10		ns
T_r	Rise Time			10		
$T_{d(off)}$	Turn-off Delay Time			68		
T_f	Fall Time			36		
E_{on}	Turn-on Switching Energy	**Inductive switching @ 25°C** V_{GS} = 15V, V_{Bus} = 800V I_D = 50A, R_G = 0.8Ω		2.79		mJ
E_{off}	Turn-off Switching Energy			0.6		
E_{on}	Turn-on Switching Energ	**Inductive switching @ 125°C** V_{GS} = 15V, V_{Bus} = 800V I_D = 50A, R_G = 0.8Ω		5.6		mJ
E_{off}	Turn-off Switching Energy			0.81		
R_{thJC}	Junction to Case Thermal Resistance				0.1	°C/W

Series diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1000			V
I_{RM}	Maximum Reverse Leakage Current	V_R=1000V				300	µA
I_F	DC Forward Current		T_c = 80°C		120		A
V_F	Diode Forward Voltage	I_F = 120A			1.9	2.5	V
		I_F = 240A			2.2		
		I_F = 120A	T_j = 125°C		1.7		
t_{rr}	Reverse Recovery Time	I_F = 120A V_R = 667V di/dt = 400A/µs	T_j = 25°C		280		ns
			T_j = 125°C		350		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		1.52		µC
			T_j = 125°C		7.2		
R_{thJC}	Junction to Case Thermal Resistance					0.46	°C/W

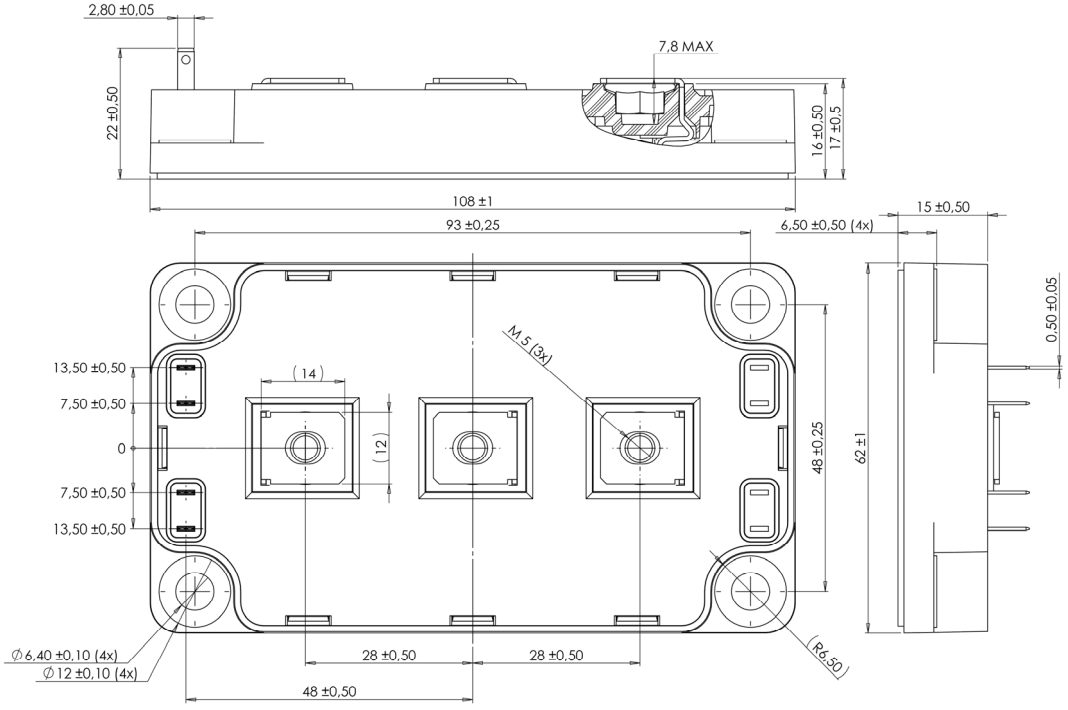
Parallel diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
V_{RRM}	Maximum Repetitive Reverse Voltage			1200			V
I_{RM}	Maximum Reverse Leakage Current	V_R=1200V				350	µA
I_F	DC Forward Current		T_c = 70°C		120		A
V_F	Diode Forward Voltage	I_F = 120A			2	2.5	V
		I_F = 240A			2.3		
		I_F = 120A	T_j = 125°C		1.8		
t_{rr}	Reverse Recovery Time	I_F = 120A V_R = 800V di/dt = 400A/µs	T_j = 25°C		400		ns
			T_j = 125°C		470		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		2.4		µC
			T_j = 125°C		8		
R_{thJC}	Junction to Case Thermal Resistance					0.46	°C/W

Thermal and package characteristics

Symbol	Characteristic			Min	Max	Unit
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000		V
T_J	Operating junction temperature range			-40	150	°C
T_{JOP}	Recommended junction temperature under switching conditions			-40	$T_J$max -25	
T_{STG}	Storage Temperature Range			-40	125	
T_C	Operating Case Temperature			-40	100	
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package Weight				300	g

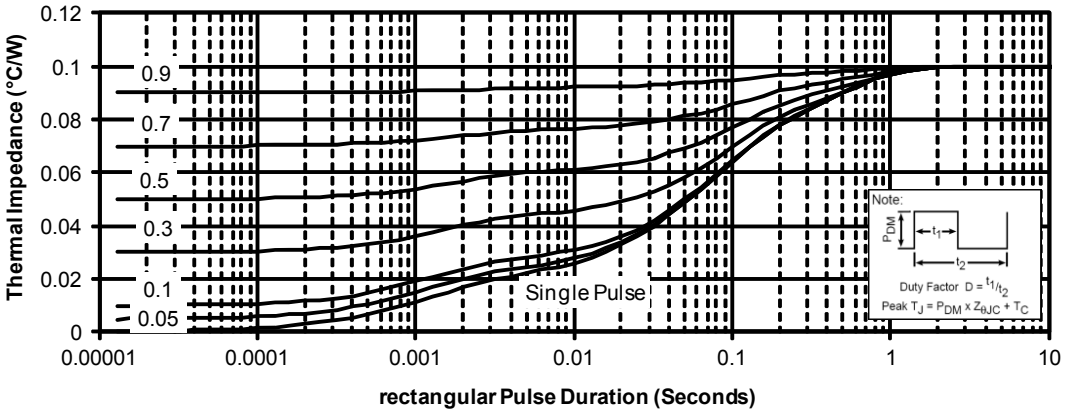
SP6 Package outline (dimensions in mm)



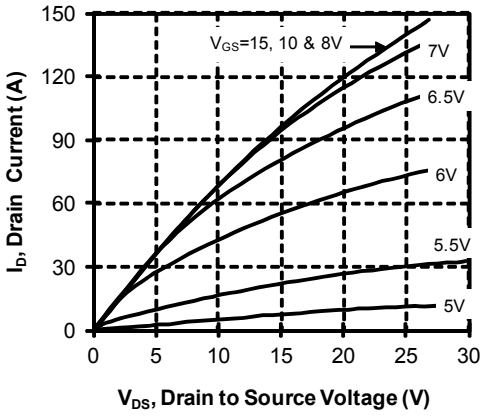
See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical Performance Curve

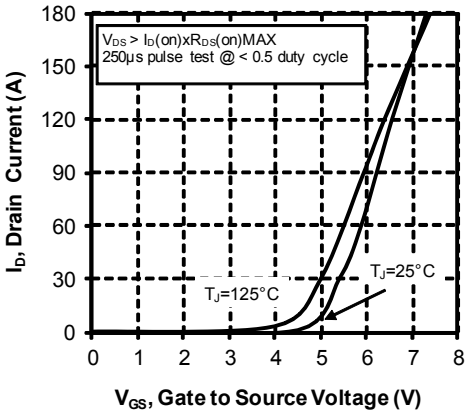
Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration



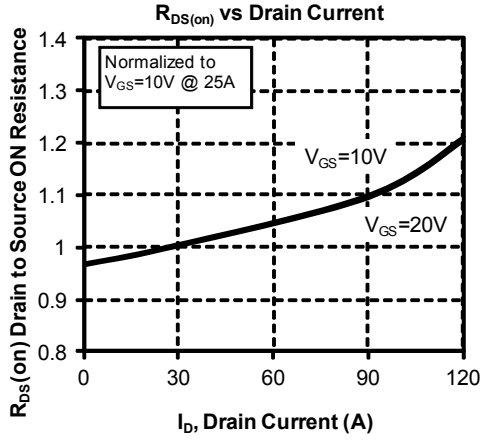
Low Voltage Output Characteristics



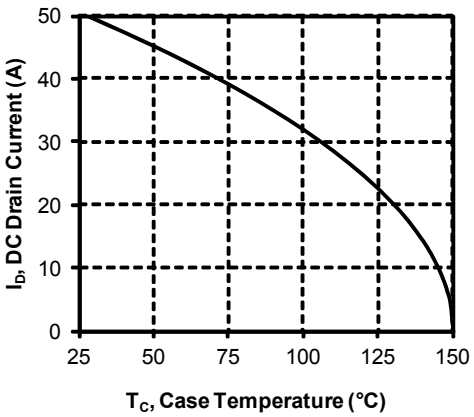
Transfert Characteristics



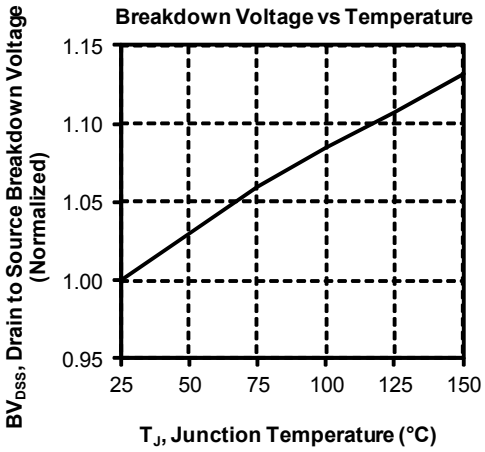
RDS(on) vs Drain Current



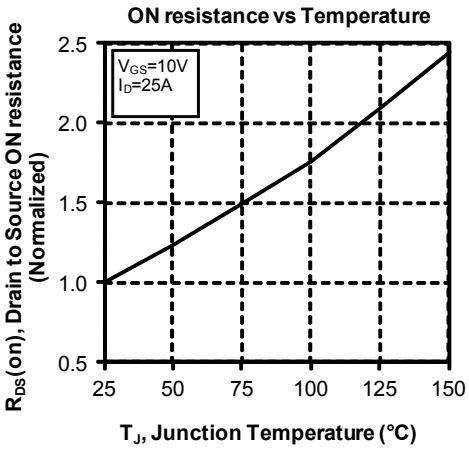
DC Drain Current vs Case Temperature



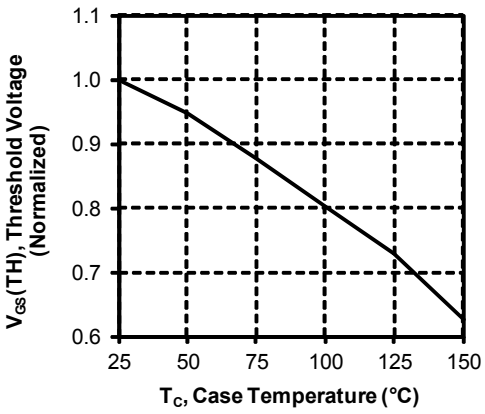
Breakdown Voltage vs Temperature



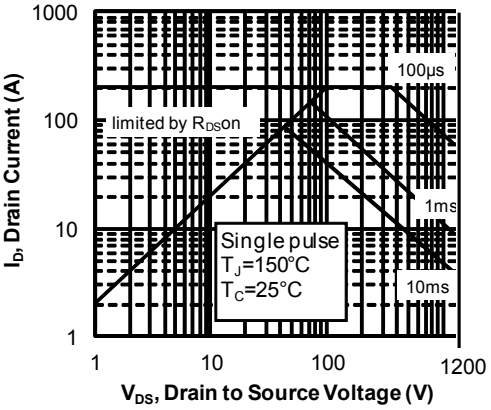
ON resistance vs Temperature



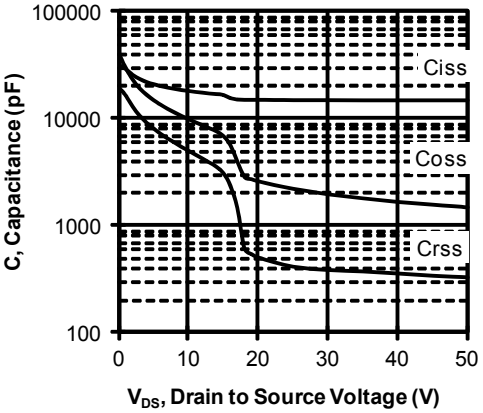
Threshold Voltage vs Temperature



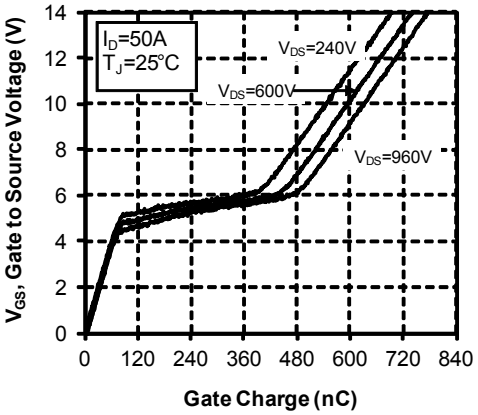
Maximum Safe Operating Area



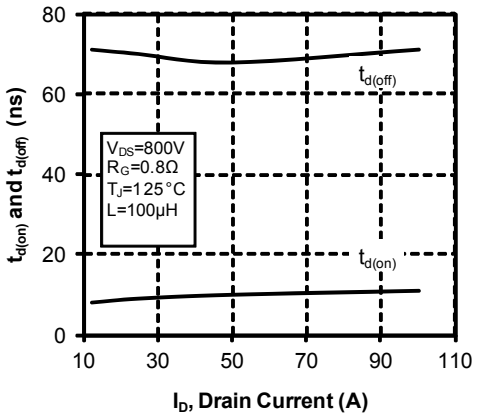
Capacitance vs Drain to Source Voltage



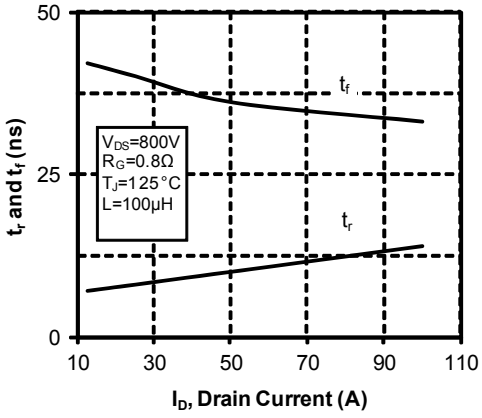
Gate Charge vs Gate to Source Voltage



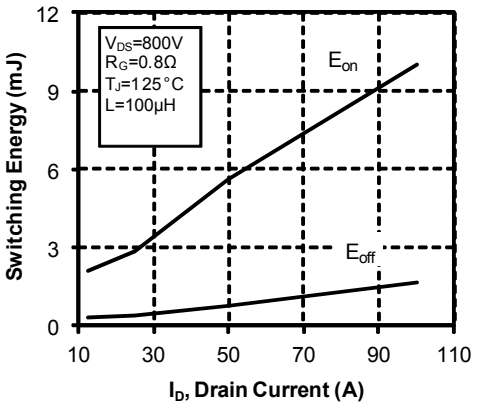
Delay Times vs Current



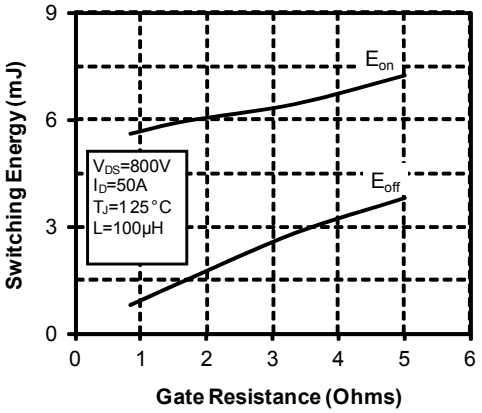
Rise and Fall times vs Current



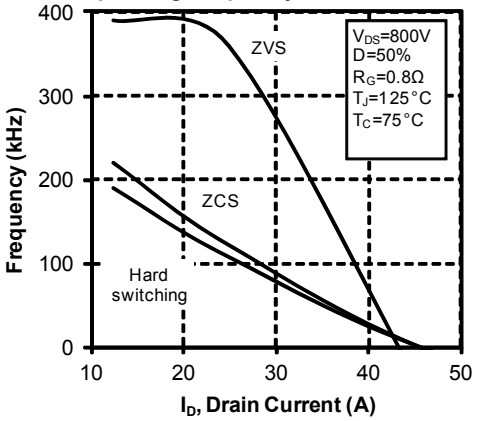
Switching Energy vs Current



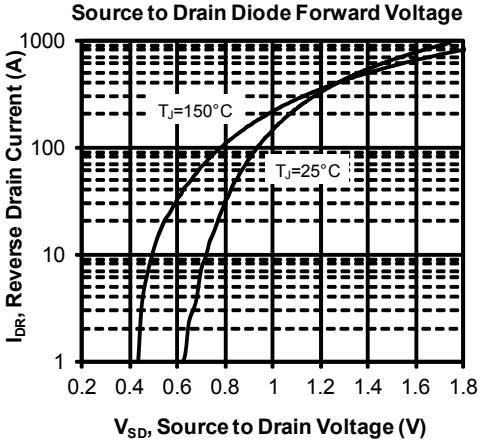
Switching Energy vs Gate Resistance



Operating Frequency vs Drain Current



Source to Drain Diode Forward Voltage



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